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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:  
Eng-Chew Cheah

Serial No. 09/863,652

Filed: May 22, 2001

Title: *Multi-Tiered Lead Package For An  
Integrated Circuit*

Attorney Docket No. 9818-050-999

Date: August 17, 2001

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REQUEST FOR CORRECTION OF FILING RECEIPT

Office of Initial Patent Examination's  
Customer Service Center  
Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

Applicant's attorney requests correction of the filing receipt for the referenced application. Please correct the domestic priority date to read:

THIS APPLN CLAIMS BENEFIT OF 60/263,495 09/29/00

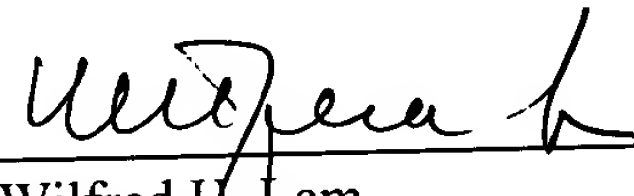
A marked up copy of the Filing Receipt for this application is enclosed.

No fee is believed to be required with this communication, however, the Commissioner is hereby authorized to charge any required fee or credit any overpayment to Pennie & Edmonds LLP Deposit Account No. 16-1150 (order no.9818-0050-999). This form is submitted in duplicate for such purpose.

Respectfully submitted,

PENNIE & EDMONDS LLP

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| APPLICATION NUMBER | FILING DATE  | GRP ART UNIT | FIL FEE REC'D | ATTY. DOCKET NO | DRAWINGS | TOT CLAIMS | IND CLAIMS |
|--------------------|--------------|--------------|---------------|-----------------|----------|------------|------------|
| 09/863,652 ✓       | 05/22/2001 ✓ | 2814 ✓       | 790           | 9818-050-999 ✓  | 3        | 19         | 4          |

24341  
Pennie & Edmonds, LLP  
3300 Hillview Avenue  
Palo Alto, CA 94304



CONFIRMATION NO. 1049 ✓

## FILING RECEIPT



\*OC00000006335618\*

Date Mailed: 07/24/2001

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

## Applicant(s)

✓ Eng-Chew Cheah, San Jose, CA;

## Domestic Priority data as claimed by applicant

THIS APPLN CLAIMS BENEFIT OF 60/263,495 01/23/2001 \*

~~(\*) Data inconsistent with PTO records.~~

09/29/00

## Foreign Applications

If Required, Foreign Filing License Granted 07/24/2001

Projected Publication Date: Request for Non-Publication Acknowledged

Non-Publication Request: Yes

Early Publication Request: No

## Title

Multi-tiered lead package for an integrated circuit ✓

## Preliminary Class

257

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